

## FlipChip International Opens Reliability & Design Center

PHOENIX, Arizona, October 11, 2004---FlipChip International, LLC today announced the opening of a Reliability & Design Center for Wafer Level Packaging and flip chip bumping technologies within its Phoenix, Arizona facility. FlipChip International is the leading provider of merchant Wafer Level Packaging (WLP) and flip chip bumping to the semiconductor market through its Phoenix facility and six global licensees.

This Reliability & Design center will support FlipChip International's design wins for radio-on-chip, wireless and broadband semiconductor devices utilized in next generation video phones and wireless sensors. Due to high customer demand, FlipChip International has installed in-house testing within the Reliability and Design Center that supports its internal and external customers' needs for accelerated tests and analytical analysis of their devices and packages.

Bob Forcier, President and CEO of FlipChip International (FCI), said, "As our customers adopt Wafer Level Packaging and flip chip bumping as an alternative to traditional chip packaging, we are excited to work directly with the semiconductor design groups on their next generation devices. This Reliability and Design Center is a key part of our ongoing expansion of flip chip services which continue to provide lower cost, smaller form factor and higher performance solutions for our customers' products."

Dr. Haluk Balkan, Vice-President of Engineering of FCI, said, "The Reliability & Design Center is a significant addition to our services, enabling us to support our customers from concept to product qualification. Now, we are in a position to provide rapid response to design inquiries, manage new product qualifications, and lead joint projects with our customers in support of their technology roadmaps. The Reliability Center is configured with accelerated test equipment including state-of-the-art electromigration testing, temperature cycling, and autoclave chambers. The analytical analysis capabilities include FTIR, DSC, UV-VIS for material characterization, wet lab, cross sectioning, X-Ray & optical inspection, and state-of-the-art SEM/EDX. This Reliability Center is part of our five year technology and product roadmap at FlipChip International."

FlipChip International, LLC (FCI) is a privately held supplier of products and services for wafer bumping and Wafer Level Packaging semiconductor market. FlipChip International, LLC is a wholly owned subsidiary of RoseStreet Labs, LLC, a supplier of products and services for wireless infrastructure in the life science, renewable energy and homeland security markets.

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